



General Description

- AlphaSGT™ N-Channel Power MOSFET
- Excellent gate charge x R_{DS(ON)} product (FOM)
- PB-free lead plating, RoHS compliant

Applications

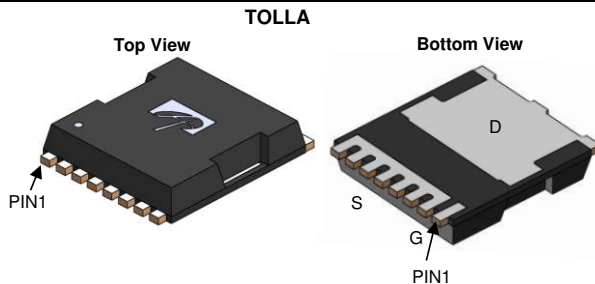
- BLDC Motor Drive
- Battery Management
- Load Switch

Product Summary

V _{DS}	80V
I _D (at V _{GS} =10V)	420A
R _{DS(ON)} (at V _{GS} =10V)	< 1.25mΩ
R _{DS(ON)} (at V _{GS} =8V)	< 1.45mΩ

100% UIS Tested
100% Rg Tested

Max T_j=175°C



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOTL66810	TOLLA	Tape & Reel	2000

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V _{DS}	80	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	T _C =25°C	420
		T _C =100°C	300
Pulsed Drain Current ^C (≤100μS)	I _{DM}	1700	A
Continuous Drain Current	I _{DSM}	T _A =25°C	65
		T _A =70°C	55
Avalanche Current ^C	I _{AS}	80	A
Avalanche energy L=0.3mH ^C	E _{AS}	960	mJ
Power Dissipation ^B	P _D	T _C =25°C	425
		T _C =100°C	210
Power Dissipation ^A	P _{DSM}	T _A =25°C	10
		T _A =70°C	7
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 175	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	R _{θJA}	t ≤ 10s	10	°C/W
Maximum Junction-to-Ambient ^{A,D}		Steady-State	35	45
Maximum Junction-to-Case	R _{θJC}	0.25	0.35	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	80			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.4	3	3.6	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A T _J =125°C		1.0 1.5	1.25 1.90	mΩ
		V _{GS} =8V, I _D =20A		1.1	1.45	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		81		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V
I _S	Maximum Body-Diode Continuous Current				200	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =40V, f=1MHz		13000		pF
C _{oss}	Output Capacitance			3300		pF
C _{rss}	Reverse Transfer Capacitance			95		pF
R _g	Gate resistance	f=1MHz	1	2	3	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =40V, I _D =20A		175	245	nC
Q _{gs}	Gate Source Charge			50		nC
Q _{gd}	Gate Drain Charge			35		nC
Q _{oss}	Output Charge	V _{GS} =0V, V _{DS} =40V		238		nC
t _{D(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =40V, R _L =2.0Ω, R _{GEN} =3Ω		35		ns
t _r	Turn-On Rise Time			25		ns
t _{D(off)}	Turn-Off Delay Time			113		ns
t _f	Turn-Off Fall Time			39		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, di/dt=500A/μs		52		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt=500A/μs		340		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 175° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.

B. The power dissipation P_D is based on T_{J(MAX)}=175° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=175° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

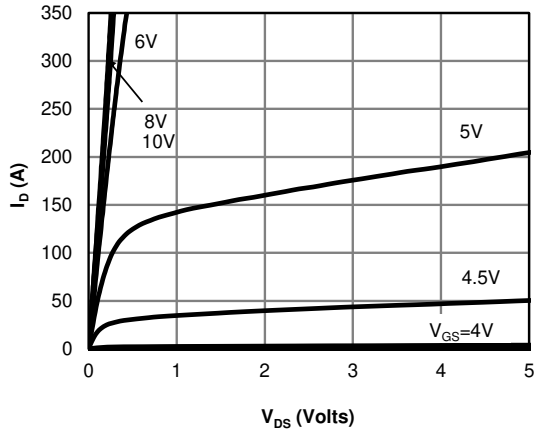


Figure 1: On-Region Characteristics (Note E)

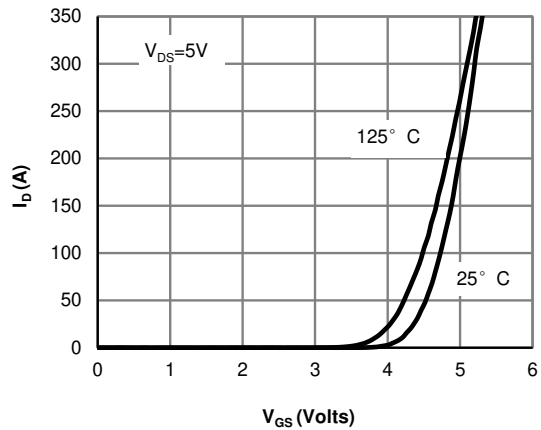


Figure 2: Transfer Characteristics (Note E)

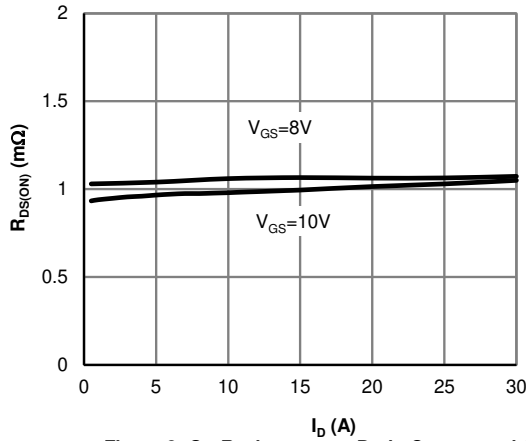


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

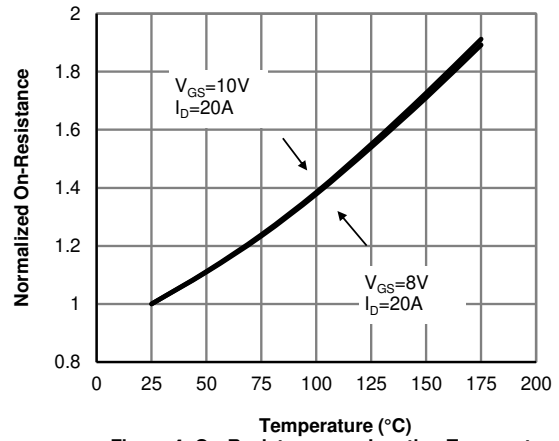


Figure 4: On-Resistance vs. Junction Temperature (Note E)

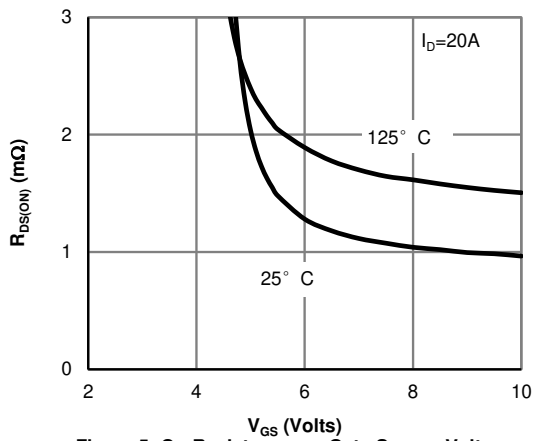


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

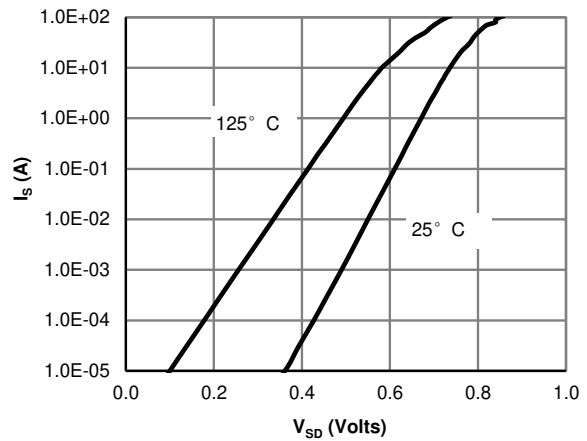


Figure 6: Body-Diode Characteristics (Note E)

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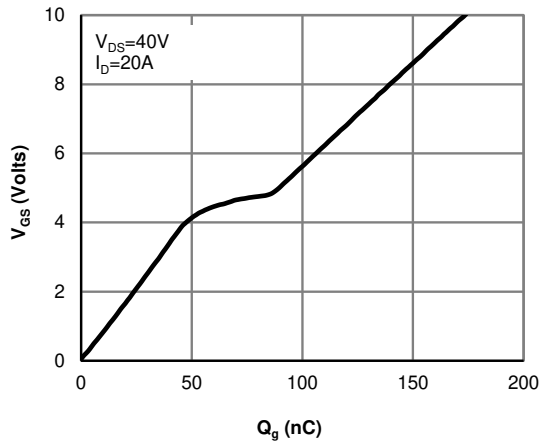


Figure 7: Gate-Charge Characteristics

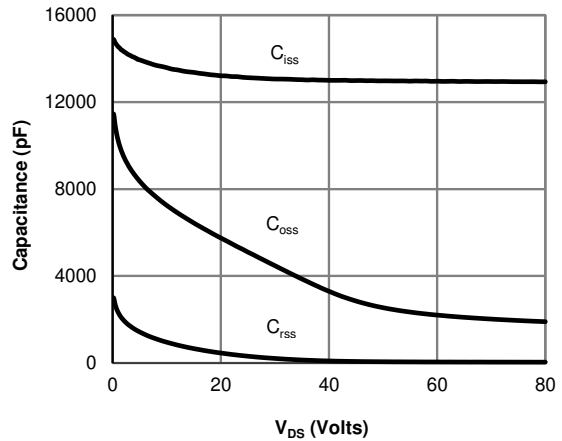


Figure 8: Capacitance Characteristics

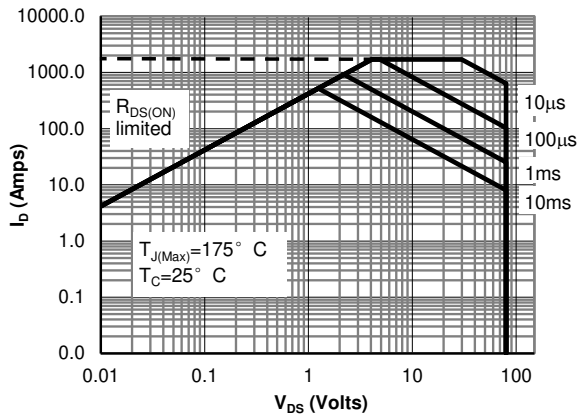


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

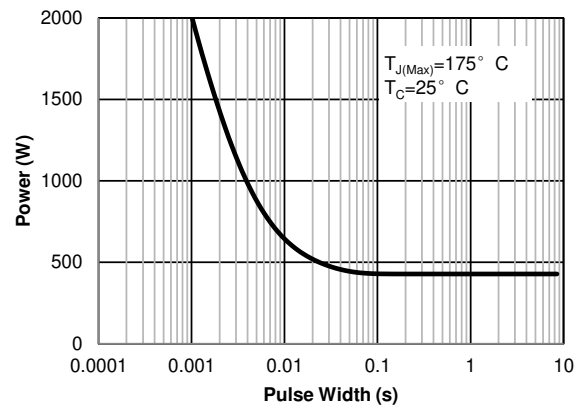


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

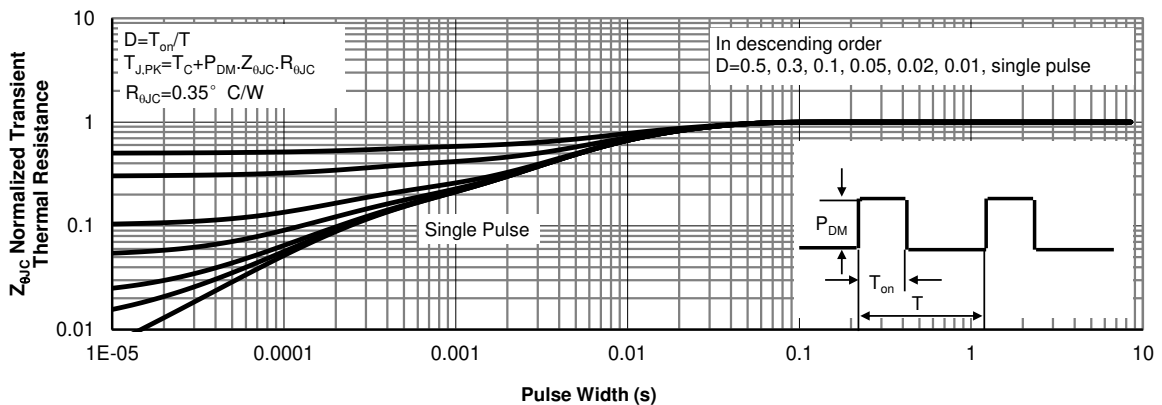


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

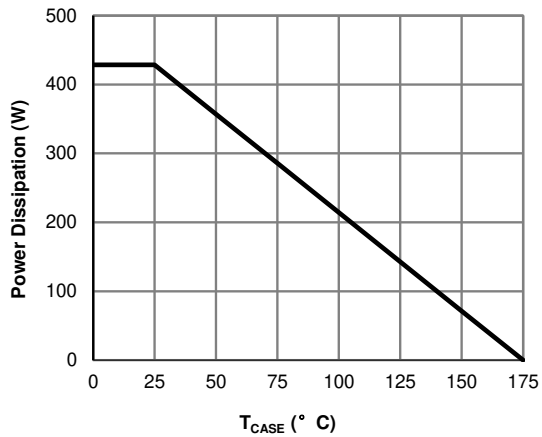


Figure 12: Power De-rating (Note F)

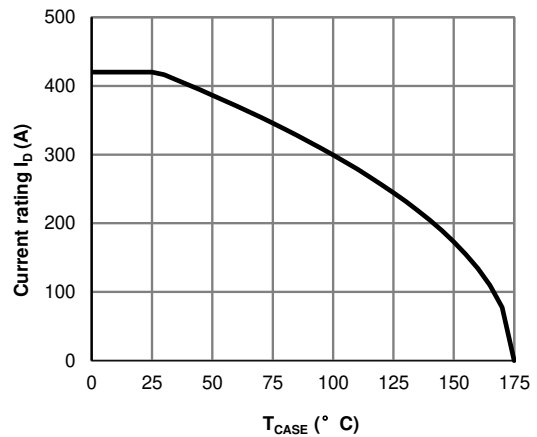


Figure 13: Current De-rating (Note F)

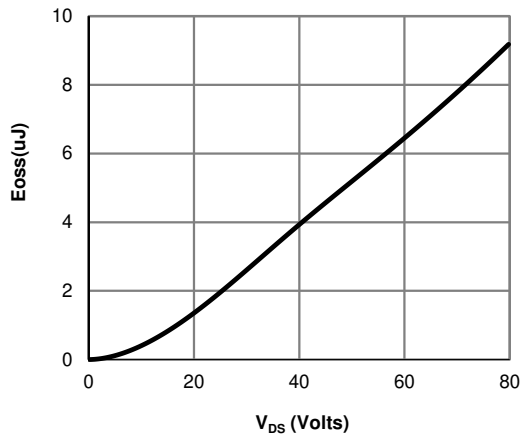


Figure 14: Coss stored Energy

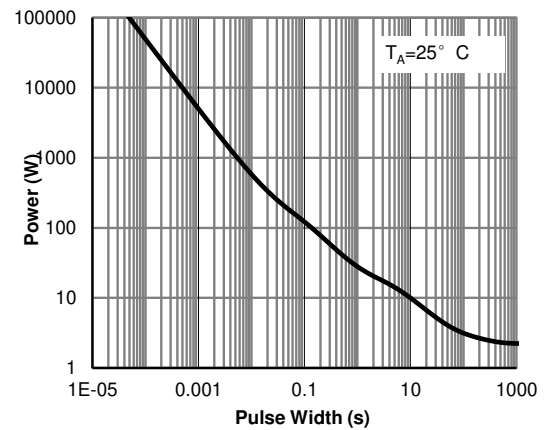


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

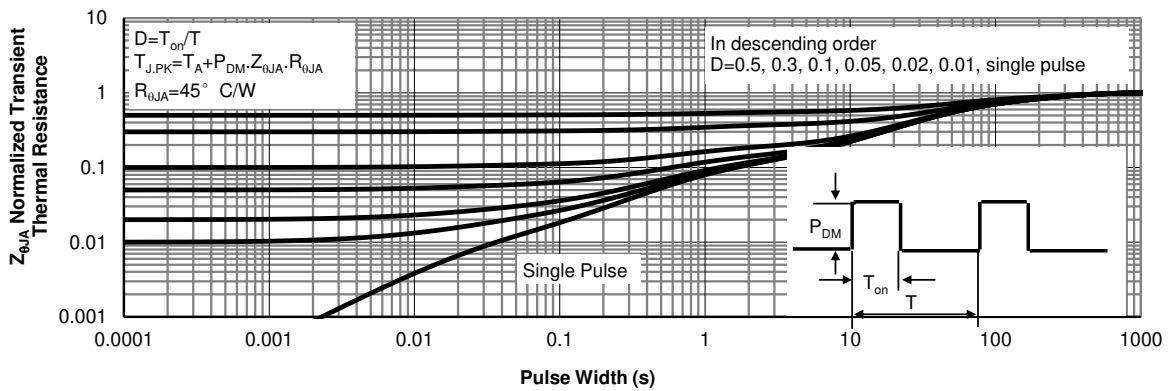


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

Figure A: Gate Charge Test Circuit & Waveforms

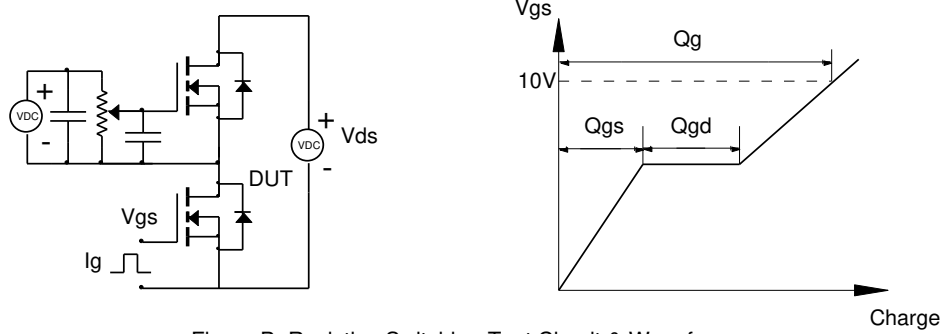


Figure B: Resistive Switching Test Circuit & Waveforms

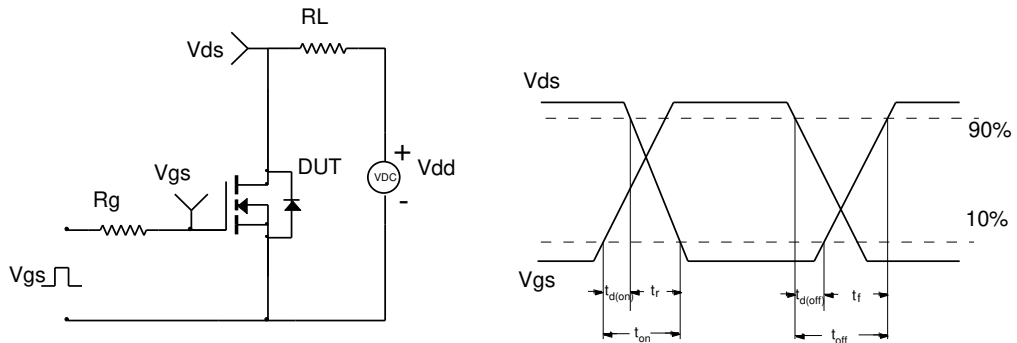


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

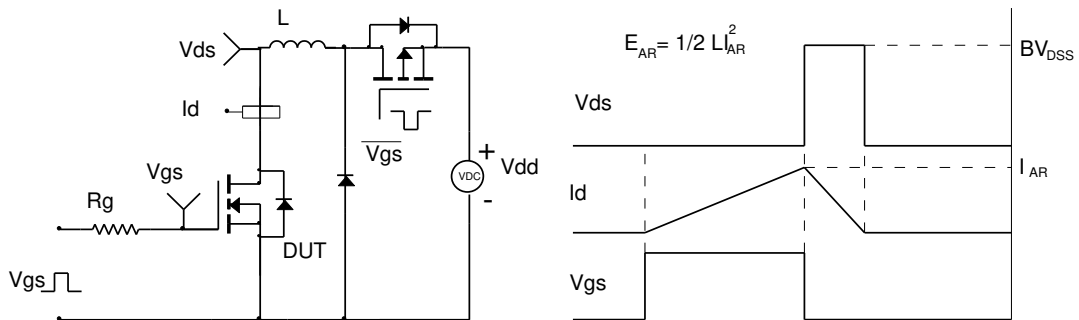


Figure D: Diode Recovery Test Circuit & Waveforms

